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SUPPLIER MUST SEND EMAIL TO EVBOLD@QORVO.COM IF JOB IS PLACED ON HOLD
 SUPPLIER SHALL SEND A COPY OF FINAL WORKING GERBERS TO CEADS@QORVO.COM

LAYER STACK LEGEND

Material	Layer	Thickness	Dielectric	Material Type	Comment
	Top Overlay			Legend	HIGH TEMPERATURE, NON-CONDUCTIVE, WHITE EPOXY BASED INK.
	Surface Material			Solder Mask	LPI (LIQUID PHOTO-IMAGEABLE) OR LDI (LASER DIRECT IMAGEABLE), GREEN.
Copper	Top Layer	0.0007in		Signal	FINISH THICKNESS
	Prepreg	0.0080in	ROGERS 4003C	Dielectric	
Copper	Bottom Layer	0.0007in		Signal	FINISH THICKNESS
Finished board thickness: 0.0104in					

NOTES: (UNLESS OTHERWISE SPECIFIED)

- BOARD FABRICATION METHODS MUST COMPLY WITH: FABRICATE IN ACCORDANCE WITH IPC-6018, CLASS 2 IAW IPC-6011
- ARTWORK FORMAT: GERBER 274X
GERBER DATA SUPPLIED WITH DESIRED FINAL TRACE WIDTHS. PROCESS COMPENSATION TRACE WIDTH ADJUSTMENTS TO BE DONE BY PCB FABRICATOR
- FINISH PLATING:
METAL 1 (TOP) AND METAL 2 (BOTTOM):
ENIG (ELECTROLESS NICKEL/IMMERSION GOLD);
ELECTROLESS NICKEL per IPC-4552, 118 - 236µin. (3 - 6µm)
IMMERSION GOLD per IPC-4552, 3 - 10 µin (0.08 - 0.25µm)
- FINISHED BOARD THICKNESS: (SEE LAYER STACKUP) +/- 10%
- COPPER IS PULLED BACK 0.010in. GROUND PLANE ONLY FROM EDGE OF BOARD ON METAL 1 (TOP) AND METAL 2 (BOTTOM), NO PULL BACK ON TAPER. THESE VALUES ARE CRITICAL AND MUST BE INSPECTED.
- TOLERANCE: PC BOARD OUTLINE: ±0.005in.
- BURRS SHALL NOT EXCEED 0.002in.
- ALL PLATED THRU HOLES TO BE PLATED TO 0.0007 ± 0.0004in. MIN. THICKNESS.
- VIA PLATING/FILLING:
ALL 0.008in AND 0.010in VIAS TO BE EPOXY-FILLED, SAN-EI KAGAKU PHP-900 NON-CONDUCTIVE EPOXY, PLANARIZED.
- CONDUCTOR WIDTHS AND SPACING TO BE WITHIN 0.001in. OF CAD DATABASE.
- ALL HOLES TO BE LOCATED WITHIN ±0.003 OF CAD DATABASE.
- 100% ELECTRICAL TEST: IPC-D-356 FORMAT.
- NO VENDOR MARKING OR SERIALIZATION ALLOWED.
- SOLDERMASK IN PLATED-THRU HOLES IS ACCEPTABLE AS LONG AS IT DOES NOT EXIST ON BACKSIDE OF BOARD.
- DELIVER BOARDS BAGGED AS: SINGLES

* FOR MULTIPLE DRILL PROCESS JOBS SEE: *DRL, *DR1, *DR2, etc.

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES	SAP MATERIAL NUMBER: 298959		
TOLERANCES .XX = ±0.01 .XXX = ±0.005 .XXXX = ±0.0010 ANGLES = ± 0.5°	APPROVAL AND RELEASE RECORDS MAINTAINED IN PDE		
INTERPRET DRAWING PER ANSIS/ASME Y14.5 - 2009	PDE CONTROLLED		TITLE: QPA4536 EVALUATION PCB DESIGN PACKAGE
THIRD ANGLE PROJECTION DO NOT SCALE DRAWING	CAGE CODE 1CVM1	SIZE: B	DOCUMENT NUMBER: QPA4536-4000
EAR	WARNING - THIS DOCUMENT CONTAINS TECHNICAL DATA WHOSE EXPORT IS UNDER CONTROL OF THE UNITED STATES DEPARTMENT OF COMMERCE UNDER THE EXPORT ADMINISTRATION REGULATIONS (15 CFR 730-774). DIVERSION CONTRARY TO U.S. LAW IS PROHIBITED. INFORMATION AND GUIDANCE ON EXPORT CONTROL REQUIREMENTS CAN BE FOUND AT www.BIS.doc.GOV		PROTOTYPE INSTANCE: N/A
		SHEET 1 OF 7	CAD: ALTIUM DESIGNER
		SCALE: 2:1	REV. A

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Current Date & Time: 7/28/2021 12:29

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